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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10078020	02/15/2002	420	557	1742	Ip Zimmerman

****APPLICANTS:** Choi Won; Goldsmith Charles; Gosselin Timothy; Henderson Donald;
Kang Sung; Puttlitz Karl; Shih Da-Yuan;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

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TITLE : Lead-free tin-silver-copper alloy solder composition

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Applicant's Examiner	
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